

SPECIFICATION

1.Material&Finish

⚠ Insulator:LCP(UL94V-0),Black
 Contact:Phosphor Bronze,Gold Flash On Contact Area And Solder Tails,Over Nickel

2.Electrical Characteristics

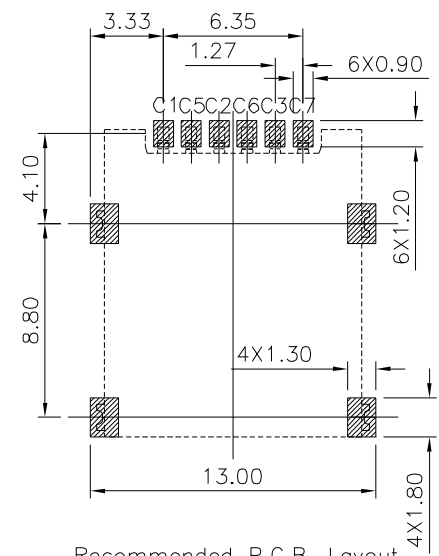
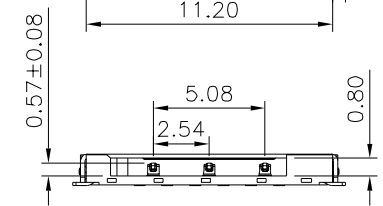
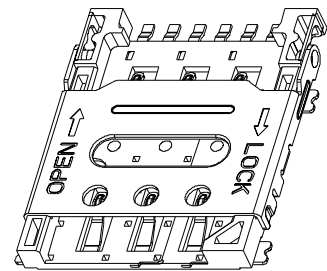
Shell:Stainless Steel,No Plated
 Current Rating:0.5A Max.
 Dielectric Withstanding Voltage:500V AC Minute
 Insulation Resistance:1000 Megaohms Min.

⚠⚠ Contact Resistance:100 Milliohms Max.

3.Mechanical Characteristics

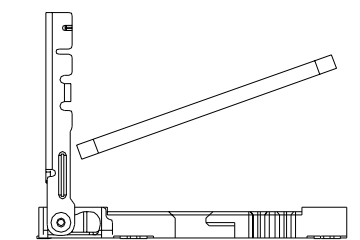
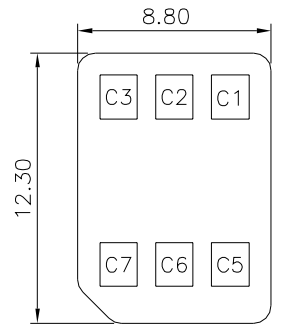
Life Cycles:3000 Cycles

4.RoHS Compliant



Recommended P.C.B. Layout
 (PCB Board Tolerance±0.05)

▨ SMT Solder Area



Step 1 Insert Nano SIM Card
 Step 2 Push The Shell
 Step 3 Finish

Pin No.	Pin Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

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 4UCON TECHNOLOGY INC.

DRAWING No.
21671

APPROVED BY MEI
 CHECKED BY HZF
 DRAWING BY CYP

UNLESS OTHERWISE SPECIFIED TOLERANCES ARE
 X. ±0.35 X.* ±5*
 .X ±0.30 .X* ±2*
 .XX ±0.25 .XX* ±1*
 .XXX ±0.15 .XXX* ±0.5*

NO.	REV.	REVISIONS	CHK	DATE
3	A3	Modify Data	HZF	12/24/2022
2	A2	Modify Data	HZF	08/17/2022
1	A1	Modify Data	HZF	01/14/2020
0	A0	NEW RELEASE	HZF	05/27/2019

SCALE NONE

REV. A3

